TOSHIBA 2SK2614

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ($L^2-\pi$ -MOS V)

2 S K 2 6 1 4

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

4 V Gate Drive

Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.032 \Omega$ (Typ.)

High Forward Transfer Admittance : $|Y_{fs}| = 8 S$ (Typ.)

: $I_{DSS} = 100 \,\mu\text{A}$ (Max.) Low Leakage Current

 $(V_{DS} = 50 V)$

: $V_{th} = 0.8 \sim 2.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

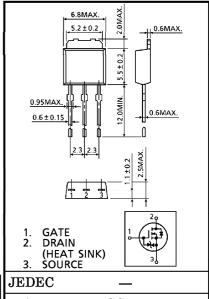
CHARACTERIST	SYMBOL	RATING	UNIT				
Drain-Source Voltage	$ m V_{DSS}$	50	V				
Drain-Gate Voltage (RGS	${ m v_{DGR}}$	50	V				
Gate-Source Voltage	v_{GSS}	±20	V				
Drain Current	DC	${ m I}_{ m D}$	20	A			
	Pulse	$I_{ m DP}$	50				
Drain Power Dissipation	$P_{\mathbf{D}}$	40	W				
Channel Temperature	$\mathrm{T_{ch}}$	150	°C				
Storage Temperature Range		$\mathrm{T_{stg}}$	-55~150	°C			

THERMAL CHARACTERISTICS

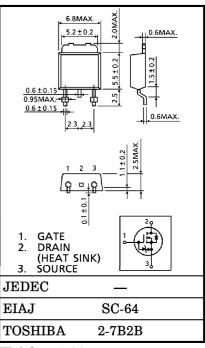
	SYMBOL		
Thermal Resistance, Channel to Case	R _{th (ch-c)}	3.125	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}		°C/W

This transistor is an electrostatic sensitive device. Please handle with caution.

INDUSTRIAL APPLICATIONS Unit in mm



JEDEC	_	
EIAJ	SC-64	
TOSHIBA	2-7B1B	



Weight: 0.36 g

961001EAA2

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

	HARACTERISTICS	(14 - 25 C)					
CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	$I_{ m GSS}$	$V_{GS} = \pm 16 V, V_{DS} = 0 V$	<u> </u>	_	±10	μ A
Drain Cut-off	f Current	$I_{ m DSS}$	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μ A
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_{\mathrm{D}} = 10 \mathrm{mA}, \; \mathrm{V}_{\mathrm{GS}} = 0 \mathrm{V}$	50	_	_	V
Gate Thresho	old Voltage	$V_{ m th}$	$V_{\mathrm{DS}} = 10 \mathrm{V}, \mathrm{I_D} = 1 \mathrm{mA}$	0.8	_	2.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 4 \text{ V}, I_D = 5 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	_	0.055	0.08	Ω
Forward Trai Admittance	nsfer	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ A}$	7	13	_	s
Input Capaci	tance	C_{iss}		_	900	_	
Reverse Transfer Capacitance		C _{rss}	$egin{aligned} { m V}_{ m DS} &= 10 { m V}, \; { m V}_{ m GS} &= 0 { m V}, \ { m f} &= 1 { m MHz} \end{aligned}$	_	130	_	pF
Output Capacitance		C_{oss}		_	370	_	
Switching Time Fall	Rise Time	t _r	V _{GS} $_{0\text{ V}}^{10\text{ V}}$ $_{\text{P1}}^{\text{I}_{D} = 10\text{ A}}$ $_{\text{Vout}}^{\text{V}_{out}}$	_	15	_	
	Turn-on Time	t _{on}	$\begin{array}{c c} & & & \\ & & & &$	_	25	_	ns
	Fall Time	tf	$\begin{array}{c c} & & \downarrow \\ & & \downarrow \\ & & V_{DD} = 30 \text{ V} \end{array}$	_	30	_	lis
	Turn-off Time	t _{off}	$V_{\mathrm{IN}}: t_r, \; t_f < 5 \; \mathrm{ns}, \ \mathrm{Duty} \leq 1\%, \; t_W = 10 \; \mu \mathrm{s}$	_	100	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 40 \text{ V}, V_{GS} = 10 \text{ V},$	_	25	_	
Gate-Source Charge		Q_{gs}	$I_D = 20 \text{ A}$	_	19	_	nC
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$		_	6	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	20	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_		50	A
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = 20 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse Recovery Time	t_{rr}	$I_{DR} = 20 \text{ A}, V_{GS} = 0 \text{ V}$		60	_	ns
Reverse Recovery Charge	$\mathrm{Q_{rr}}$	$dI_{DR}/dt = 50 A/\mu s$	_	45		μ C

MARKING

